ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Par	PC. Bannockl	burn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration en declaration en	on of the su compasses	bstances w all lower	vithin the manufactu level materials for w	rer listed which the 1	item. Note: nanufacture	if the item is an as r has engineering	sembly with low responsibility.	
				Form Type Distribute					ials and Mfg Information					
upplier Information														
Company name* Cor			Company unique ID			Unique ID Authority				Respon	Response Date*			
nsemi										2023-06-08				
ontact Name Title - Contact			:t			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product En			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Re			Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version Manufacturing Site			Weight*	UOM	Unit Type		
	CNY17I	VY17F2SM 6PW NO-B T		R SMD		2023-06-08		TI	ТНН		464.903	mg	Each	
Ianufacturing Proccess Informa	tion					·								
Terminal Plating / Grid Array M	aterial T	Ferminal Base	Alloy J-STD-020 MSL Ra		Rating	Peak Proce	Process Body Temperatu		ure Max Time at Peak Temper		ture Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU A		CU Alloy	1			<b>260</b> C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak temperatu	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a that agreement, will be the sole and exclusives	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe ve independently verified such information. How heir contributions to the part, and those certifica anditions of that agreement, including any warr	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the Terms andConditions of Sale applicable to such part shall apply.									
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the pomit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	0.4	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.04	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		0.36	mg
Die	5.13	mg	Supplier	Silicon (Si)	7440-21-3		5.13	mg
Die Attach	0.3	mg	Supplier	Silver (Ag)	7440-22-4		0.225	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.075	mg
Lead Frame	101.703	mg	Supplier	Silver (Ag)	7440-22-4		0.407	mg
			Supplier	Zinc (Zn)	7440-66-6		0.203	mg
			Supplier	Iron (Fe)	7439-89-6		2.64	mg
			Supplier	Copper (Cu)	7440-50-8		98.3	mg
			Supplier	Phosphorus (P)	7723-14-0		0.153	mg
Mold Compound-White	327.22	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		81.805	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		9.8166	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		44.1747	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		9.8166	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		163.61	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		17.9971	mg
Plating	28.5	mg	Supplier	Tin (Sn)	7440-31-5		28.5	mg
Wire Bond - Au	1.65	mg	Supplier	Gold (Au)	7440-57-5		1.65	mg